

Abstract

The present invention provides a visual system of a bonding device, a method for determining position and posture of a workpiece to be bonded, and a computer-readable storage medium. The visual system of a bonding device comprises a plurality of imaging modules and a view field adjustment mechanism. The plurality of imaging modules are used to capture an image of a plurality of markers on a workpiece to be bonded, so as to characterize a position and/or an orientation of the workpiece to be bonded. The view field adjustment mechanism is used to rotate at least one of the imaging modules, adjusting a view field position thereof, to cover the plurality of markers on the workpiece to be bonded. The present invention can be used to collect an image of a plurality of markers on a workpiece to be bonded, to improve the bonding efficiency of wafer bonding process by rotating and adjusting view field positions of a plurality of imaging modules.

(FIG. 1)